

View Online at https://aerobasegroup.com/nsn/5910-01-379-5026

Body Style: Chip type **Reliability Indicator:** Established **Reliability Failure Rate Level In Percent:** 0.001 **Terminal Length:** 0.5 millimeters **Body Length:** 2.0 millimeters **Body Width:** 1.25 millimeters **Body Height:** 1.3 millimeters Schematic Diagram Designator: No common or grounded electrode (s) Insulation Resistance At Maximum Operating Temp: 1000.0 megohms **Capacitance Value Per Section:** 220.000 picofarads single section Nonderated Operating Temp: Between -55.0 degrees celsius and 125.0 degrees celsius Tempurature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius: 0.0 single section Nonderated Continuous Voltage Rating And Type Per Section: 100.0 dc single section **Tolerance Of Tempurature Coefficient Per Section In Ppm Per Deg Celsius:** -30.0/+30.0 single section **Tolerance Range Per Section:** -1.00/+1.00 percent single section **Case Material:** Ceramic Insulation Resistance At Reference Temp: 1000000.0 megohms **Dissipation Factor At Reference Tempurature In Percent:** 0.150 **Terminal Surface Treatment:** Solder **Test Data Document:** 81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain

environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).

Terminal Type And Quantity:

2 bonding pad



Specification Data:

81349-mil-c-55681/07 government specification

Shelf Life:

N/a

Unit Of Measure:

Demilitarization:

No

Fiig:

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